

Title (en)

DEVICE AND METHOD FOR JOINING THIN, FLAT ELEMENTS

Title (de)

VORRICHTUNG UND VERFAHREN ZUM VERBINDEN VON DÜNNEN, FLÄCHIGEN ELEMENTEN

Title (fr)

DISPOSITIF ET PROCEDE POUR RELIER DES ELEMENTS FINS ET PLANS

Publication

EP 1807248 A1 20070718 (DE)

Application

EP 05796324 A 20051011

Priority

- EP 2005010940 W 20051011
- DE 102004052871 A 20041102

Abstract (en)

[origin: WO2006048099A1] The invention relates to a device for joining thin, flat elements (12a, 12b) by means of an adhesive, comprising a transport unit (9) which is used to transport the flat elements (12a, 12b) through the device, and a device (2) for producing microwaves in order to harden an adhesive which is applied to the edges of the flat elements (12a, 12b). The invention is characterised in that the microwaves are guided into a wave guide (3) which comprises at least one slot (4). The butt joint (13) of the flat elements (12a, 12b) comprising the adhesive can be guided past the slit (4) in order to harden the adhesive by means of the microwaves emerging from the slit (4). The invention also relates to a method for joining thin, flat elements.

IPC 8 full level

B27D 1/10 (2006.01); **H05B 6/78** (2006.01); **H05B 6/80** (2006.01)

CPC (source: EP)

B27D 1/10 (2013.01); **H05B 6/705** (2013.01); **H05B 6/708** (2013.01); **H05B 6/78** (2013.01)

Citation (search report)

See references of WO 2006048099A1

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)

DE 102004052871 A1 20060504; AT E399081 T1 20080715; DE 502005004541 D1 20080807; EP 1807248 A1 20070718; EP 1807248 B1 20080625; WO 2006048099 A1 20060511

DOCDB simple family (application)

DE 102004052871 A 20041102; AT 05796324 T 20051011; DE 502005004541 T 20051011; EP 05796324 A 20051011; EP 2005010940 W 20051011